CALL FOR PAPERS

IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

32nd International Electronics Manufacturing Technology Symposium (IEMT 2007)

October 3-5 2007, San Jose/Silicon Valley, California, USA

The 32nd International Electronics Manufacturing Technology (IEMT) Conference is the premier IEEE event devoted to the manufacture (mainly the assembly/packaging aspects) of electronic, opto-electronic and MEMS/sensors devices and systems. IEMT is an established International conference of long standing organized by the Components Packaging and Manufacturing Technology (CPMT) Society of IEEE. IEMT 2007 is being co-organized by the Santa Clara Valley Chapter of CPMT.

Through well-mediated technical papers IEMT offers manufacturing technologists as well as designers a single convenient forum to assess new packaging and assembly technologies about to enter production or in production around the world. In addition, IEMT also provides attendees the opportunity to meet leading domain experts and network with colleagues.

As the design of devices and systems on one hand and their manufacture on the other get increasingly separated over geographies, it becomes critical to provide a single forum where the challenges and opportunities arising from this new paradigm can be mastered. Therefore in 2007 a strong theme of IEMT will be outsourcing – challenges, networking, opportunities and systems, with emphasis on off-shore capabilities and case studies.

In addition to approximately 70 technical papers over 2.5 days, IEMT '07 will also feature several Professional Development Courses. It is co-located this year with the CPMT Society's Advanced Packaging Materials Symposium.

Conference Topics: Abstracts are sought from fabless companies, manufacturers (integrated, contract manufacturing service providers) and their suppliers on proven capabilities and case studies for package assembly/manufacturing of electronic, solar, opto-electronic, MEMS, bio-medical, display panels and systems including but not limited to the following topics:

Sourcing & Supply Chain Networking
- IP Protection/use, Licensing, Technology Gaps
- Offshore/Nearshore/Onshore Experiences
- Management across Multi-companies, Partner Selection, Qual.
- Electronics Manufacturing Services Optimization, Challenges
- Consequences of the Supply Chain
- Impact on Logistics, Product Development , Quality, Schedule

Manufacturing
- DFM, Assembly, Processes, Optimization, Automation
- Cost-Reduction, Quality, Management Systems
- Modeling and Simulation
- Producing Subsystems: GPS, Bluetooth, Cameras, Appliances
- Transferring Processes and Tooling
- Latest Technologies in near-Implementation, Production
- Application-based Reliability Standards
- Innovations in Bonders, Fiber Alignment, Batch vs Continuous
- Predictive Models for Excursion Detection, Yield, Cost-Reduction

Testing
- DFT Methodologies, Best Practices
- Transferring Processes and Tooling
- Test Planning and Implementation
- Subsystem and System Testing

Design for Environment, Recycling
- Impact of new Materials and Processes on Manufacturing
- Green (Pb and halide free), ROHS Experience
- Effective Implementations
- WEEE and Return Legislation Effects
- Design for Cost-Effective Recycling, Disassembly

Applications as Templates
- Using Generic Process Platforms
- Cell Phone/etc for Portable, Low-pwr, High-density, WLP, 3D
- Display Assemblies, Electronic Paper
- LEDs for Illumination; MEMS/MOEMS/Sensors
- Solar and Energy Conversion/Conservation

Packaging Integration Issues
- SOP, SiP, Stacked/3D, WLP Production Issues
- Substrate/Package Issues
- Methods and Solutions
- Practical Issues
- Embedded Passives/Waveguides

Implications of Nanotechnology
- Nanotechnology in Production
- Packaging with Nano, Handling Nano, Nano Safety
- Applying Leading-Edge Technology to Manufacturing

III. Abstract and Paper Requirements

An abstract of approximately 500 words that summarizes original and previously unpublished work such as case studies, research, development and applications are welcomed. The abstract should clearly state the purpose, methodology, results, and conclusions of the work. The selection process is competitive and sufficient details need to be included to allow the Technical Program Committee to assess the content of the proposed paper**.** Abstracts must be received by **APRIL 30.** Selected Authors will be informed of paper acceptance by **MAY 30**. Selected papers will be due in final form by **JULY 31** and should be 4 to 7 pages in length (incl. text and graphics). For further details visit **www.cpmt.org/iemt**

For further information, please contact:

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